

OSCILLATION METHOD OF WAFER OSCILLATION APPARATUS, AND WAFER OSCILLATION APPARATUS AND CHEMICAL PLATING DEVICE

ABSTRACT

The present application relates to an oscillation method of a wafer oscillation apparatus, and a wafer oscillation apparatus and a chemical plating device. The method comprises: controlling an oscillation frame to move from a first position to a second position, wherein the first position is located above the second position, and both the first position and the second position are lower than a liquid level in a process tank of a chemical plating device; and controlling a first speed to be within a first preset speed range when the oscillation frame reaches the second position and before the oscillation frame stops movement, such that the oscillation frame can generate vibration of a first preset amplitude when stopping movement. By means of the oscillation method of a wafer oscillation apparatus, the wafer oscillation apparatus and the chemical plating device in the present application, the uniformity of a plated layer can be improved.

Fig 3.